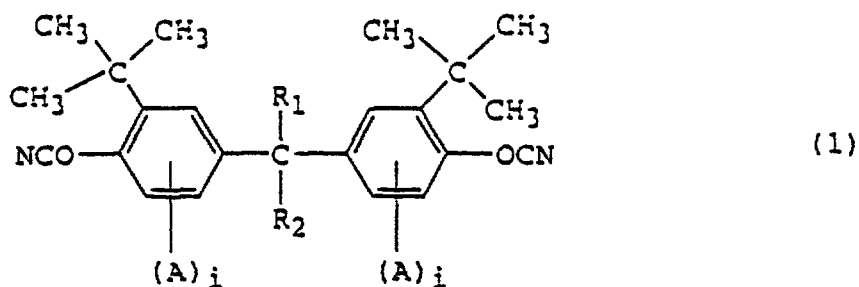


ABSTRACT

CYANATE RESIN COMPOSITION AND COPPER-CLAD LAMINATE USING THE COMPOSITION

A cyanate resin composition comprising as essential components a cyanate compound represented by formula (1) or its prepolymer and a curing agent:



wherein each of R_1 and R_2 represents a hydrogen atom or an alkyl group having 1 to 5 carbon atoms; A represents an alkyl group having 1 to 3 carbon atoms; i represents an integer of 0 to 3 alone or together with a brominated epoxy compound or a maleimide compound or its prepolymer, said cyanate resin composition giving a cured product having a low-dielectric constant, and a copper-clad laminate composed of a prepreg of said cyanate resin composition and a copper foil.